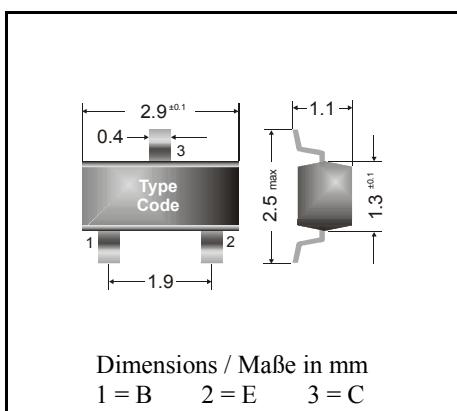


PNP

Surface mount Si-Epitaxial PlanarTransistors Si-Epitaxial PlanarTransistoren für die Oberflächenmontage

PNP



Power dissipation – Verlustleistung	250 mW
Plastic case Kunststoffgehäuse	SOT-23 (TO-236)
Weight approx. – Gewicht ca.	0.01 g
Plastic material has UL classification 94V-0 Gehäusematerial UL94V-0 klassifiziert	
Standard packaging taped and reeled Standard Lieferform gegurtet auf Rolle	

Maximum ratings ($T_A = 25^\circ\text{C}$)**Grenzwerte ($T_A = 25^\circ\text{C}$)**

			BCX 71
Collector-Emitter-voltage	B open	$- V_{CEO}$	45 V
Collector-Base-voltage	E open	$- V_{CBO}$	45 V
Emitter-Base-voltage	C open	$- V_{EBO}$	5 V
Power dissipation – Verlustleistung	P_{tot}	250 mW ¹⁾	
Collector current – Kollektorstrom (DC)	$- I_C$	100 mA	
Peak Collector current – Kollektor-Spitzenstrom	$- I_{CM}$	200 mA	
Peak Base current – Basis-Spitzenstrom	$- I_{BM}$	200 mA	
Junction temperature – Sperrschiichttemperatur	T_j	150°C	
Storage temperature – Lagerungstemperatur	T_s	- 65...+ 150°C	

Characteristics ($T_j = 25^\circ\text{C}$)**Kennwerte ($T_j = 25^\circ\text{C}$)**

	Min.	Typ.	Max.
Collector-Base cutoff current – Kollektorreststrom $I_E = 0, - V_{CB} = 32 \text{ V}$	$- I_{CB0}$	–	–
$I_E = 0, - V_{CB} = 32 \text{ V}, T_j = 150^\circ\text{C}$	$- I_{CB0}$	–	20 nA
$I_E = 0, - V_{EB} = 4 \text{ V}$	$- I_{EB0}$	–	20 μA
Emitter-Base cutoff current – Emitterreststrom $I_C = 0, - V_{EB} = 4 \text{ V}$	$- I_{EB0}$	–	20 nA
Collector saturation volt. – Kollektor-Sättigungsspg. ²⁾ $- I_C = 10 \text{ mA}, - I_B = 0.25 \text{ mA}$	$- V_{CESat}$	60 mV	–
$- I_C = 50 \text{ mA}, - I_B = 1.25 \text{ mA}$	$- V_{CESat}$	120 mV	250 mV
		–	550 mV

¹⁾ Mounted on P.C. board with 3 mm^2 copper pad at each terminal
Montage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluß

²⁾ Tested with pulses $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300 \mu\text{s}$, Schaltverhältnis $\leq 2\%$

Characteristics ($T_j = 25^\circ\text{C}$)Kennwerte ($T_j = 25^\circ\text{C}$)

		Min.	Typ.	Max.
Base saturation voltage – Basis-Sättigungsspannung ¹⁾				
- $I_C = 10 \text{ mA}$, - $I_B = 0.25 \text{ mA}$	- V_{BEsat}	600 mV	–	850 mV
- $I_C = 50 \text{ mA}$, - $I_B = 1.25 \text{ mA}$	- V_{BEsat}	700 mV	–	1050 mV
DC current gain – Kollektor-Basis-Stromverhältnis ¹⁾				
$- V_{CE} = 5 \text{ V}$, $- I_C = 10 \mu\text{A}$	BCX 71G	h_{FE}	–	–
	BCX 71H	h_{FE}	30	–
	BCX 71J	h_{FE}	40	–
	BCX 71K	h_{FE}	100	–
$- V_{CE} = 5 \text{ V}$, $- I_C = 2 \text{ mA}$	BCX 71G	h_{FE}	120	–
	BCX 71H	h_{FE}	180	–
	BCX 71J	h_{FE}	250	–
	BCX 71K	h_{FE}	380	–
$- V_{CE} = 1 \text{ V}$, $- I_C = 50 \text{ mA}$	BCX 71G	h_{FE}	60	–
	BCX 71H	h_{FE}	80	–
	BCX 71J	h_{FE}	100	–
	BCX 71K	h_{FE}	110	–
Base-Emitter voltage – Basis-Emitter-Spannung ¹⁾				
- $V_{CE} = 5 \text{ V}$, $- I_C = 10 \mu\text{A}$	- V_{BEon}	–	550 mV	–
- $V_{CE} = 5 \text{ V}$, $- I_C = 2 \text{ mA}$	- V_{BEon}	600 mV	650 mV	750 mV
- $V_{CE} = 1 \text{ V}$, $- I_C = 50 \text{ mA}$	- V_{BEon}	–	720 mV	–
Gain-Bandwidth Product – Transitfrequenz				
- $V_{CE} = 5 \text{ V}$, $- I_C = 10 \text{ mA}$, $f = 100 \text{ MHz}$	f_T	100 MHz	–	–
Collector-Base Capacitance – Kollektor-Basis-Kapazität				
- $V_{CB} = 10 \text{ V}$, $I_E = i_e = 0$, $f = 1 \text{ MHz}$	C_{CBO}	–	4.5 pF	–
Emitter-Base Capacitance – Emitter-Basis-Kapazität				
- $V_{EB} = 0.5 \text{ V}$, $I_C = i_c = 0$, $f = 1 \text{ MHz}$	C_{EBO}	–	11 pF	–
Noise figure – Rauschzahl				
- $V_{CE} = 5 \text{ V}$, $- I_C = 200 \mu\text{A}$, $R_G = 2 \text{ k}\Omega$, $f = 1 \text{ kHz}$, $\Delta f = 200 \text{ Hz}$	F	–	2 dB	6 dB
Thermal resistance junction to ambient air Wärmewiderstand Sperrschiicht – umgebende Luft		R_{thA}		420 K/W ²⁾
Recommended complementary NPN transistors Empfohlene komplementäre NPN-Transistoren			BCX 70 series	

Marking
Stempelung

BCX 71G = BG

BCX 71H = BH

BCX 71J = BJ

BCX 71K = BK

¹⁾ Tested with pulses $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$ – Gemessen mit Impulsen $t_p = 300 \mu\text{s}$, Schaltverhältnis $\leq 2\%$ ²⁾ Mounted on P.C. board with 3 mm^2 copper pad at each terminalMontage auf Leiterplatte mit 3 mm^2 Kupferbelag (Lötpad) an jedem Anschluß